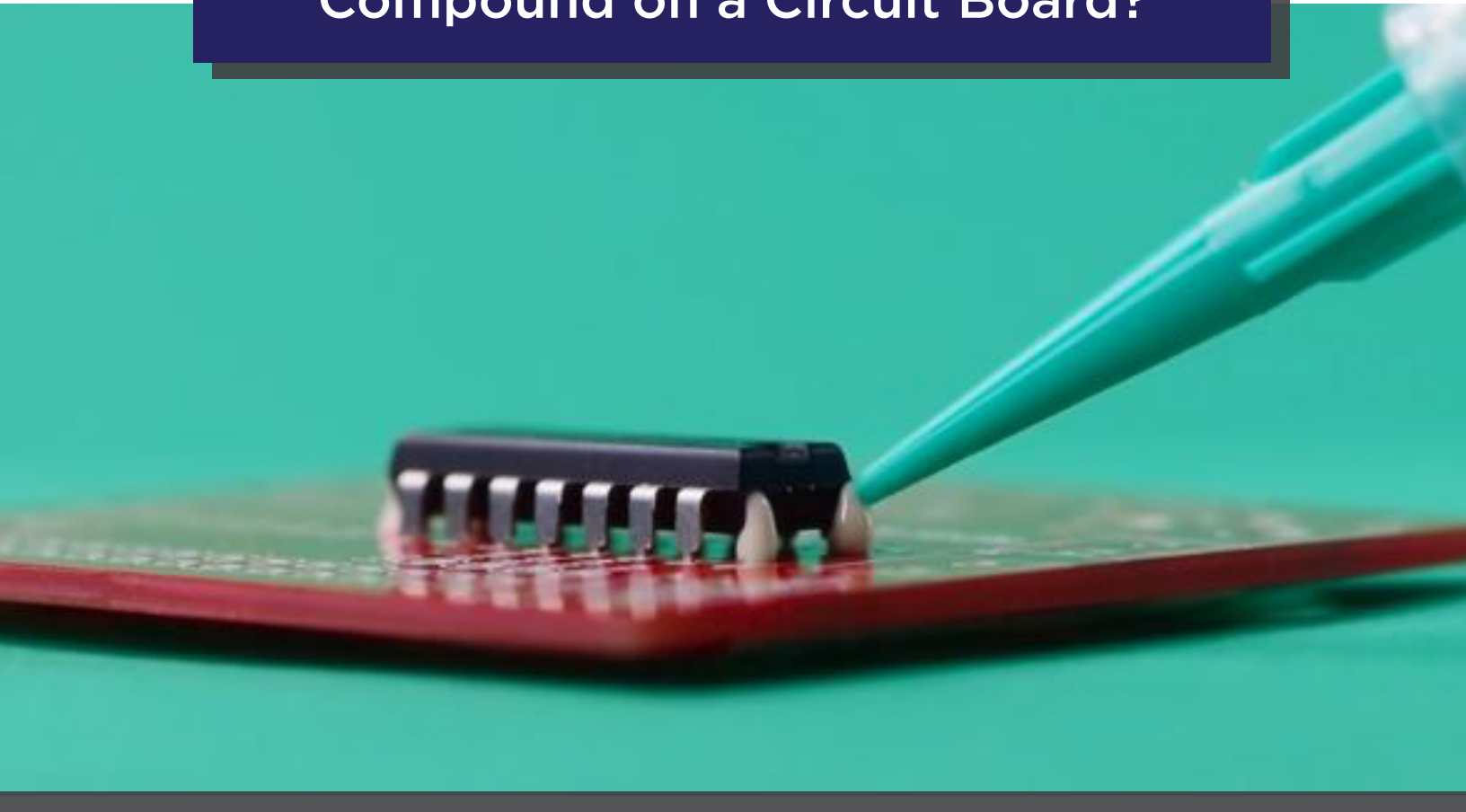


How Do You Use a Staking Compound on a Circuit Board?



WHY USE A STAKING COMPOUND?

The main use for adhesive staking is to provide extra mechanical support for electronic components and other parts that may be damaged due to vibration, shock or handling. Different components require different methods of staking.

Continue reading for a step-by-step instructional guide on staking electronic components to a circuit board.

How Do You Use a Staking Compound on a Circuit Board?



1 STAKING A DUAL IN-LINE PACKAGE (DIP) COMPONENT

A *DIP component* requires staking at the four corners using a fine tip syringe with a high viscosity compound.

The goal is to connect the corners of the component to the circuit board while ensuring that the material does not flow under the component.



2 STAKING A CAPACITOR

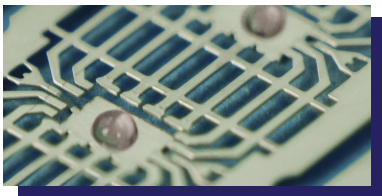
Capacitors often require staking for enhanced stability. In this case, the material is applied to the edge of the component while making mechanical connection with the circuit board.

Note: *There are other ways to stake a capacitor including staking at more than one location or even applying the material around the entire component.*



3 AFTER APPLYING STAKING COMPOUND

The material should be cured based on the instructions on the technical data sheet.



STAKING COMPOUND EXAMPLE: EP17HTDA-1

One part epoxy system EP17HTDA-1 is a thermally conductive, electrically insulative material featuring a thixotropic paste viscosity. It cures in one to two hours at 350°F with minimal shrinkage.



Prefer to watch a step by step video?

Scan to see a demonstration on applying a staking compound to securely bond an electronic component to a circuit board